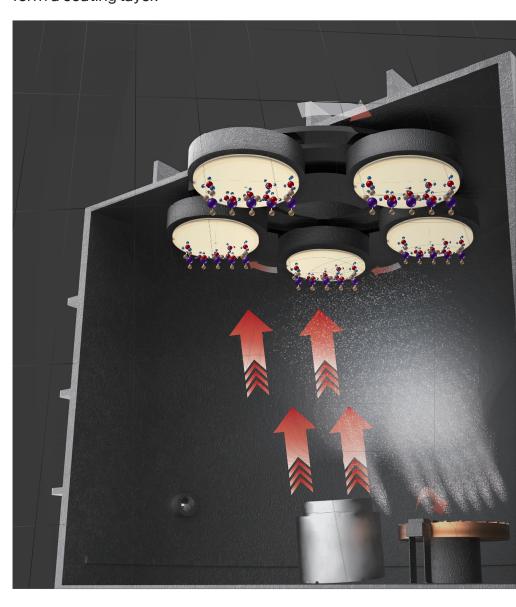
# **EP-ZERON™**

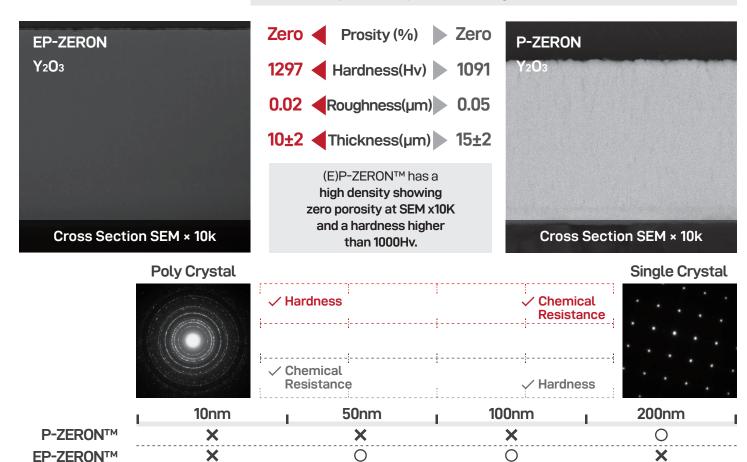
EP-ZERON<sup>TM</sup> coating is a PVD (Physical Vapor Deposition) coating technology and, P-ZERON Sputtering method and EP-ZERON is an **E-Beam evaporation coating technology that is advantageous for forming an ultra-high-density coating film.** In the E-Beam evaporation technology, the pellet  $(Y_2O_3)$  is vaporized using the electron beam, and the vaporized molecules are accelerated with the ion beam to form a coating layer. In the case of sputtering PVD, plasma is formed with Ar gas and ionized Ar atoms collide with the target (Yttrium) to release atoms (Y) and react with the internal reactive gas  $(O_2)$  gas to form a coating layer.





## **Property**

CINOS PVD coating secures various grains, so it is possible to provide a coating suitable for chamber characteristics.



# **Benefit**

CINOS PVD coating has superior physical properties to APS, SPS, and AD coating and has **the smallest change** in a plasma environment, so it can be applied to the ceramic window on the upper part of the etch chamber.

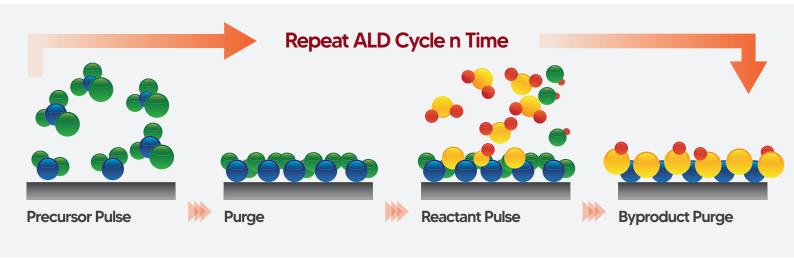
	APS(1Gen)	SPS(2Ge	en) AD(3	3Gen)	PVD	PVD	
Roughness							
Hardness		Normal	Ggod	Excellent		{	
Adhesion		A	Guod	EXCERTE		;	
Porosity							



## /E MAKE GLOBAL STANDARD

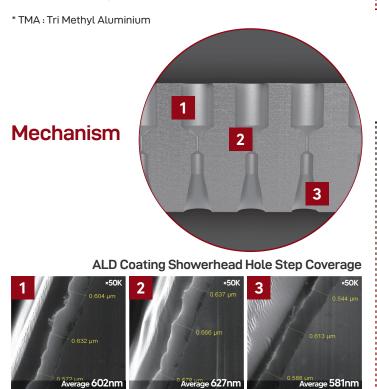






#### Al<sub>2</sub>O<sub>3</sub> Coating

A-ZERON™ Al<sub>2</sub>O<sub>3</sub> coating is formed with TMA\* (Al(CH<sub>3</sub>)<sub>3</sub>) as the precursor and H<sub>2</sub>O as the reactant. A-ZERON Al<sub>2</sub>O<sub>3</sub> coating is formed as a uniform coating layer inside and on the entire surface of the showerhead hole of the CVD process, increasing the surface hardness and reducing the reactivity with the gas used in the CVD process to extend the lifetime and reuse cycle of parts.



### Y<sub>2</sub>O<sub>3</sub> Coating

A-ZERON<sup>TM</sup>  $Y_2O_3$  coating can be coated at 100nm level and has a grain size of 600nm or more, so chemical resistance and plasma resistance are strong.

